ASSOCIATION CONNECTI ELECTRONICS INDUSTRI	Material Composition © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	ll rights reserved untions.	under both	This docum level parts, t	ent is a declara he declaration	tion of the encompass	substances es all lowe	within the manufacture level materials for w	arer listed which the	item. Note: if manufacturer	the item is an as has engineering	ssembly with lower responsibility.		
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					rials and I	als and Mfg Information				
Supplier Inform	mation															
Company name*			Company unique ID				Unique ID Authority					Response Date*				
onsemi										2024-0	2024-04-27					
Contact Name		Title - Contact				Phone - Contact*				Email	Email - Contact*					
Product-Env-Stewards			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
Authorized Repres	sentative*	Title - Representative				Phone - Representative*				Email	Email - Representative*					
Product-Env-Stew	vards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com					
Reques	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Dat	e Version Manufacturing Site			Weight*	UOM	Unit Type			
		MC74ACT652DWG LOC		LOG CMOS BUS INTRFCE OCTL		2024-04-27		]	PH1		661.78	mg	Each			
Manufacturing	g Proccess Information	1						-								
Terminal Plating / Grid Array Material Termi			erminal Base A	minal Base Alloy J-STD-020 MSL		L Rating	Peak Pro	Peak Process Body Temperatur		re Max Time at Pea	k Temper	ature Numb	er of Reflow Cy	cles		
Matte Tin (Sn) - annealed CU Allo			U Alloy	3			260 C 30			seconds 3						
Comments																
ATTENTION: MS	SL 3 Rated item requires Ba	ke and D	ry Pack (after	electrical test)												
for more informat	tion regarding material con	position	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.79	mg	Supplier	Silicon (Si)	7440-21-3		3.79	mg
Die Attach	24.58	mg	Supplier	Silver (Ag)	7440-22-4		18.435	mg
			Supplier	Epoxy resins	129915-35-1		6.145	mg
Lead Frame	385.08	mg	Supplier	Silver (Ag)	7440-22-4		2.6956	mg
			Supplier	Zinc (Zn)	7440-66-6		0.4621	mg
			Supplier	Iron (Fe)	7439-89-6		9.0494	mg
			Supplier	Copper (Cu)	7440-50-8		372.7574	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1155	mg
Mold Compound-Black	242.16	mg		Epoxy Phenol Resin	proprietary data		25.4268	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		216.7332	mg
Plating	5.6	mg	Supplier	Tin (Sn)	7440-31-5		5.6	mg
Wire Bond - Au	0.57	mg	Supplier	Gold (Au)	7440-57-5		0.57	mg